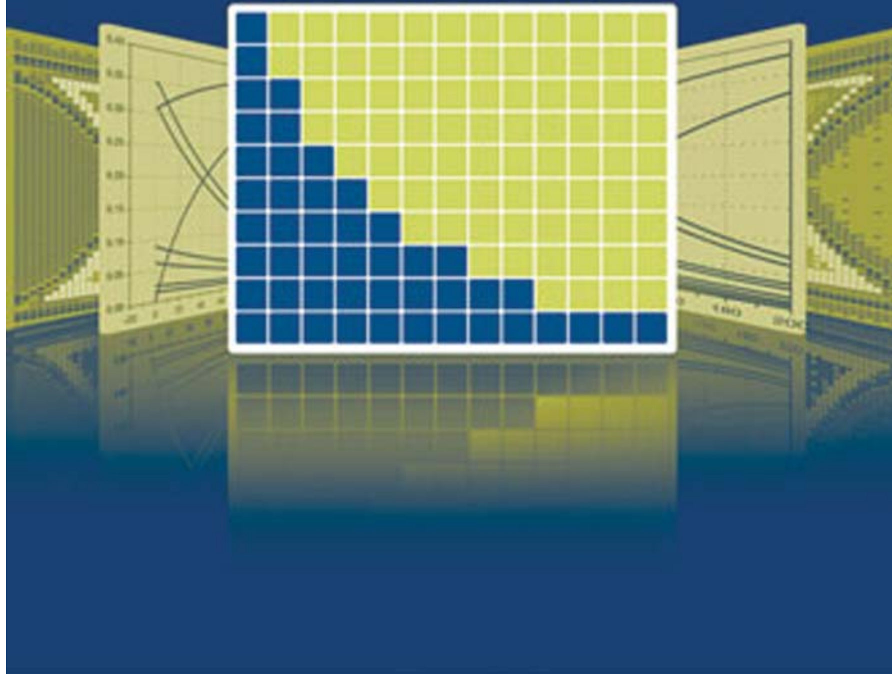
Jose Moreira • Hubert Wekmann

AN ENGINEER'S GUIDE TO

AUTOMATED TESTING OF HIGH-SPEED INTERFACES



An Engineer's Guide to Automated Testing of High-Speed Interfaces

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An Engineer's Guide to Automated Testing of High-Speed Interfaces

José Moreira
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Para os meus pais Inês e José e o meu irmão Carlos
— José Moreira

For everyone who supported me getting to the next levels
— whenever, wherever
— Hubert Werkmann

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